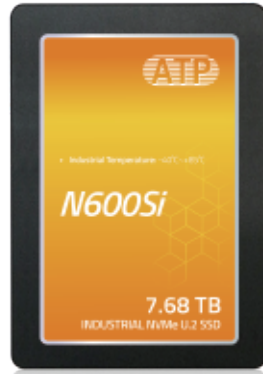




High-Density Thermal U.2 NVMe

Targeted Product Portfolio, Engineered Specifically for Your Mission Critical Applications



Key Features

- Thermal Management Solutions*
- High-Capacity NVMe Drive
- LDPC & RAID Data Recovery
- End-to-End Data Protection
- S.M.A.R.T / TRIM / Global Wear Leveling

* Customization available on a project basis

Product Name		High-Capacity U.2
		U.2
Product Line		Superior
Naming		N600Si
Flash Type		TLC
Density		960 GB to 7.68 TB
Performance	Sequential Read up to (MB/s)	3,100
	Sequential Write up to (MB/s)	1,400
Interface		PCIe G3x4, NVMe
Operating Temperature (Tcase)*		-40°C to 85°C
Reliability TBW** (max.)		21,000 TB
Reliability MTBF @ 25°C		>2,000,000 hours
Dimensions: L x W x H (mm)		100 x 69.85 x 7

Technologies & Add-On Services	S.M.A.R.T.	TCG Opal 2.0	Advanced Wear Leveling	AutoRefresh	Dynamic Data Refresh	Secure Erase	Industrial Temperature	End-to-End Data Protection	Hardware-based Power Loss Protection
Superior	•	•	•	•	•	•	•	•	•

* Case Temperature, the composite temperature as indicated by SMART temperature attributes.

** Under highest Sequential write value. May vary by density, configuration and applications.

Product spec and its related information are subject to change without advance notice.
Please refer to www.atpinc.com for latest information

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The Global Leader in Specialized Storage and Memory Solutions

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